

# PRODUCT CHANGE NOTICE

# Alternate Manufacturing Site for Assembly of Intersil ODFN Packaged Products

Refer to: PCN10053

**Date: May 26, 2010** 



May 26, 2010

To: Our Valued Intersil Customer

Subject: Alternate Manufacturing Site for Assembly of Intersil ODFN Packaged Products – Hana Microelectronics Public Co., Ltd. Lamphun, Thailand

This notice is to inform you that Intersil will begin using the Hana Microelectronics Lamphun facility as an alternate site for assembly of ODFN (Optical Dual Flat No-Lead Plastic) packaged products. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. The package and site-specific qualification activities are complete.

The Hana Microelectronics Lamphun facility is ISO 9001:2000, ISO/TS 16949, and ISO 14001:2004 certified. There will be no change in the package outline drawing (POD) or moisture sensitivity level (MSL). The qualified material set combinations are as follows:

Material	Present	Hana	
Mold Compound	Inabata 2000 series	Nitto NT-8038	
Die Attach	Sumitomo CRM 1084	Sumitomo CRM 1084	

The assembly qualification plan is designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. A summary of the qualification results is included. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, shipment, etc.) will continue to be processed to previously established conditions and systems.

Product affected by this change is identifiable via Intersil's internal traceability system and by the assembly site code (country of assembly) when marked on the devices. The site code for product assembled at the Hana facility is "E".

Intersil will take all necessary actions to conform to customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product assembled at either the current or the newly qualified sites beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

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PCN10053

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# **Qualification Summary – PCN10053**

### Hana Semiconductor 6 Lead ODFN and 8 Lead Mini-ODFN Package Qualification Summary (using ISL29011 and ISL29015)

### Summary

Test Name	Conditions	Duration	# of Lots	Sample Size	Rejects	
HAST BIASED	+110°C, 85%RH	264	3	90	0	
HAST UNBIAS	+110°C, 85%RH	264	6	180	0	
HTOL	+105°C	1000	6	158	0	
TEMP CYCLE	-40°C TO +105°C	1000	6	180	0	
ТНВ	+85°C, 85%RH	1000	3	78	0	

### **Failure Rate Calculations**

High Temperature Operating Life Failure Rates Derated to +55°C							
Rejects	Sample Size	FITs at 60% UCL	MTTF at 60% UCL				
0	158	220.25	4.54e+06				

### Notes:

An activation energy of 0.7eV is assumed when calculating failure rates for samples with 0 rejects.

Failure rate estimates are highly dependant on available device hours (or sample sizes). The device hours for this report are below what Intersil considers as adequate for an accurate statistical sample. The failure rate on this report is provided for information purposes only.



# **Products Affected – PCN10053**

# **8 Lead Devices**

ISL29011IROZ-T7
ISL29011IROZ-T7S2378
ISL29011IROZ-T7S2426
ISL29011IROZ-T7S2720
ISL29011IROZ-T7S2722
ISL29011IROZ-T7S2724
ISL29011IROZ-T7S2726
ISL29011IROZ-T7S2728
ISL29021IROZ-T7

## **6 Lead Devices**

ISL29009IROZ-T7 ISL29012IROZ-T7 ISL29015IROZ-T7 ISL29015IROZ-T7S2378 ISL29020IROZ-T7 ISL29020IROZ-T7S2568 ISL29101IROZ-T7 ISL29102IROZ-T7